## 505217308 12/04/2018

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5264076

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chen-Yi Weng	11/27/2018
Jing-Yin Jhang	11/27/2018
Hui-Lin Wang	11/27/2018
Chin-Yang Hsieh	11/27/2018

#### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16208566

### **CORRESPONDENCE DATA**

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: WINSTON HSU

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Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3369USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	12/04/2018

### **Total Attachments: 8**

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PATENT REEL: 047663 FRAME: 0798

505217308



PATENT REEL: 047663 FRAME: 0799

## Title of Invention:

## SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:			
The attached application, or				
☐ United States application number		filed on		, or
☐ PCT international application	number	filed	on	
The above-identified application was	made or authorized to be	e made by me.		
I believe that I am the original inventapplication.	or or an original joint inve	ntor of a claimed	invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri	false statement made in sonment of not more that	this declaration in five (5) years, o	s punishable r both.	
In consideration of the payment by	UNITED MICROELE CORP.	CTRONICS	having a postal add	dress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Pa	rk, Hsin-Chu (	City 300, Taiwar	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	ol of the sum of One Doll d valuable consideration.	ar (\$ 1.00), the re	ceipt of which is he	ereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, an	nd to any and all improve tion and, in and to, all Let any continuations, contir	ments which are d ters Patent to be nuation-in-part, di	disclosed in the obtained for said visions, renewals,	IEE
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or end n this assignment;	cumbrance has be	een or will be made	or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said invention ar cessary or desirable to ca	nd said Letters Pa arry out the propo	tent and said ses thereof.	
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), in s form. Use this form for g	cluding naming the	ne entire ventor.	

Page 1 of 8

NPO#NAU-P3369-USA:0 CUST#UMCD-2018-0366

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Chen-Yi Weng	Date:	NOV 2 7 2018			
Signature:	Chen Y: Weng					

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NPO#NAU-P3369-USA:0 CUST#UMCD-2018-0366

### Title of Invention:

## SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

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☐ PCT international application	number	filed on		
The above-identified application was	made or authorized to be made	by me.		
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the		
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this de- isonment of not more than five (5	claration is punishable ) years, or both.		
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu City 300, Taiwan,	R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	00), the receipt of which is here	eby	
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Par r any continuations, continuation-	vhich are disclosed in the tent to be obtained for said in-part, divisions, renewals,	Ε	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar h this assignment;	nce has been or will be made o	or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	olication, said invention and said lecessary or desirable to carry out	Letters Patent and said the proposes thereof.		
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>				

Page 3 of 8

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Jing-Yin Jhang

Date: NOV 2 7 2018

Signature: Jim Yin Jham

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NPO#NAU-P3369-USA:0 CUST#UMCD-2018-0366

### Title of Invention:

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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Pa r any continuations, continuation-	which are disclosed in tent to be obtained for in-part, divisions, rene	the r said ewals,	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar h this assignment;	nce has been or will b	e made or	
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention and said lecessary or desirable to carry out	Letters Patent and sai the proposes thereof		
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor				

Page 5 of 8

NPO#NAU-P3369-USA:0 CUST#UMCD-2018-0366

LEGAL NAME OF INVENTOR(ASSIGNOR)

inventor:

Hui-Lin Wang

Date:

NOV 2 7 2018

Signature:

Page 6 of 8

NPO#NAU-P3369-USA:0 CUST#UMCD-2018-0366

# Title of Invention: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

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☐ United States application number		filed o	_filed on, or		
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	ol of the sum of One Dollard valuable consideration.	ar (\$ 1.00), the r	eceipt of which is t	hereby	
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improven tion and, in and to, all Lett any continuations, contin	nents which are ters Patent to be uation-in-part, o	e disclosed in the e obtained for said divisions, renewals,	,	
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or enc n this assignment;	umbrance has l	been or will be mad	de or	
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention an ecessary or desirable to ca	d said Letters F irry out the prop	Patent and said poses thereof.		
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Page 7 of 8

Docket No NAUP3369USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

**Chin-Yang Hsieh** 

Date:

NOV 2 7 2018

Signature:

chin-Yang Hsieh

NPO#NAU-P3369-USA:0 CUST#UMCD**-**2018-0366

**RECORDED: 12/04/2018** 

Page 8 of 8

F#NPO-P0002E-US1201 DSB0-107U029805

PATENT REEL: 047663 FRAME: 0807